CLAIMS

What is claimed is:

1. An apparatus for preventing damage to a chamber wall by a baffle plate in a semiconductor fabrication system during a semiconductor fabrication operation, said apparatus comprising:

an electrostatic chuck associated with said semiconductor fabrication system;

a gauge for measuring a gap between said baffle plate and said chamber wall, hereby preventing damage to said chamber wall by said baffle plate during a movement of said electrostatic chunk during said semiconductor fabrication operation of said semiconductor fabrication system.

- 2. The apparatus of claim 1 wherein said semiconductor fabrication operation comprises a wet cleaning semiconductor operation.
- 3. The apparatus of claim 1 wherein said gauge is adapted for use in leveling said electrostatic chunk.
- 4. The apparatus of claim 1 wherein said gauge comprises a horizontal gap gauge.

- 5. The apparatus of claim 1 wherein said gauge is adapted for use in preventing polymer peeling of said chamber wall.
- 6. The apparatus of claim 1 wherein said gauge comprises a leveling gauge.
- 7. The apparatus of claim 1 wherein said semiconductor fabrication system comprises dual-rotate-magnet (DRM).
- 8. The apparatus of claim 7 wherein said semiconductor fabrication system comprises a focus ring.
- 9. The apparatus of claim 8 wherein said movement of said electrostatic chunk during said semiconductor fabrication operation comprises a vertical movement.
- 10. The apparatus of claim 8 wherein said movement of said electrostatic chunk during said semiconductor fabrication operation comprises a horizontal movement.

11. A method for preventing damage to a chamber wall by a baffle plate in a semiconductor fabrication system during a semiconductor fabrication operation, said method comprising the steps of:

moving an electrostatic chuck associated with said semiconductor fabrication system during said semiconductor fabrication operation; and

measuring a gap between said between said baffle plate and said chamber wall utilizing a gauge integrated with said semiconductor fabrication system, in response to moving said electrostatic chunk to thereby prevent damage to said chamber wall by said baffle plate.

- 12. The method of claim 11 wherein said semiconductor fabrication operation comprises a wet cleaning semiconductor operation.
- 13. The method of claim 11 wherein said gauge is adapted for use in leveling said electrostatic chunk.
- 14. The method of claim 11 wherein said gauge comprises a horizontal gap gauge.

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- 15. The method of claim 11 wherein said gauge is adapted for use in preventing polymer peeling of said chamber wall.
- 16. The method of claim 11 wherein said gauge comprises a leveling gauge.
- 17. The method of claim 11 wherein said semiconductor fabrication system comprises dual-rotate-magnet (DRM).
- 18. The method of claim 17 wherein said semiconductor fabrication system comprises a focus ring.
- 19. The method of claim 18 wherein said movement of said electrostatic chunk during said semiconductor fabrication operation comprises a vertical movement.
- 20. The method of claim 18 wherein said movement of said electrostatic chunk during said semiconductor fabrication operation comprises a horizontal movement.